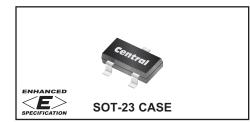


ENHANCED SPECIFICATION SURFACE MOUNT DUAL, IN SERIES SILICON SWITCHING DIODES





www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMPD7000E is an Enhanced version of the CMPD7000 Dual, Series Configuration, Ultra-High Speed Switching Diode. This device is manufactured by the epitaxial planar process, in an epoxy molded surface mount SOT-23 package, designed for high speed switching applications.

MARKING CODE: C5CE

FEATURED ENHANCED SPECIFICATIONS:

- BV_R from 100V min to 120V min.
- ♦ V_F from 1.1V max to 1.0V max.

MAXIMUM RATINGS: (T _A =25 °C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	120	V
Average Forward Current	IO	200	mA
Peak Forward Current	IFM	500	mA
Power Dissipation	Ρ _D	350	mW
Operating and Storage Junction Temperature	TJ, Tstg	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (TA=25°C unless otherwise noted)

				,	
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
IR	V _R =50V			300	nA
IR	V _R =50V, T _A =125°C			100	μA
IR	V _R =100V			500	nA
♦ BV _R	I _R =100μA	120	150		V
♦ V _F	I _F =1.0mA	0.55	0.59	0.65	V
♦ V _F	I _F =10mA	0.67	0.72	0.77	V
♦ V _F	I _F =100mA	0.85	0.91	1.0	V
CT	V _R =0, f=1.0MHz		1.5	2.6	pF
t _{rr}	$I_R=I_F=10$ mA, $R_L=100\Omega$, Rec. to 1.0mA		2.0	4.0	ns

Enhanced Specification

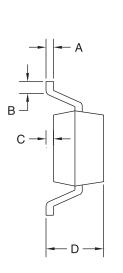
R4 (27-January 2010)

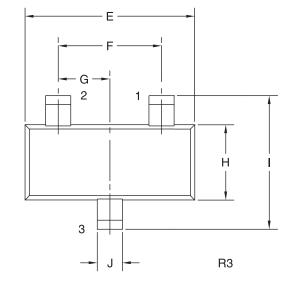




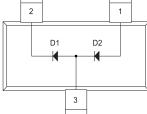
ENHANCED SPECIFICATION SURFACE MOUNT DUAL, IN SERIES SILICON SWITCHING DIODES

SOT-23 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



LEAD CODE:

1) Anode D2

- 2) Cathode D1
- 3) Anode D1, Cathode D2

MARKING CODE: C5CE

DIMENSIONS							
INCHES		MILLIMETERS					
MIN	MAX	MIN	MAX				
0.003	0.007	0.08	0.18				
0.006	-	0.15	-				
-	0.005	-	0.13				
0.035	0.043	0.89	1.09				
0.110	0.120	2.80	3.05				
0.075		1.90					
0.037		0.95					
0.047	0.055	1.19	1.40				
0.083	0.098	2.10	2.49				
0.014	0.020	0.35	0.50				
	INC MIN 0.003 0.006 - 0.035 0.110 0.00 0.00 0.047 0.083	INCHES MIN MAX 0.003 0.007 0.006 - 0.035 0.043 0.110 0.120 0.037 0.037 0.047 0.055 0.083 0.098	INCHES MILLIM MIN MAX MIN 0.003 0.007 0.08 0.006 - 0.15 - 0.005 - 0.035 0.043 0.89 0.110 0.120 2.80 0.075 1.1 0.037 0.0 0.043 0.89 0.110 0.120				

SOT-23 (REV: R3)

R4 (27-January 2010)

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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